

International  
UON Collider  
Collaboration



# 3TeV collider transverse beam stability studies

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Thanks to F. Batsch, C. Carli, H. Damerau, I. Karpov,

General design meeting

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# Goal and scope of the study

- Get a first estimate of the vacuum chamber radius achievable w.r.t transverse beam stability
- Investigate different materials for the chamber
- Important input for the magnet design
  - Chamber radius is an input for the radial build model (see L. Bottura presentation <https://indico.cern.ch/event/1162890/>)

# *Assumptions and simulation parameters*



# Impedance simulations parameters

- 1.5 TeV per beam, 4.5 km long beam chamber
- Scan the chamber radius from 10 mm to 40 mm
- Scan also the chamber material

## Machine parameters

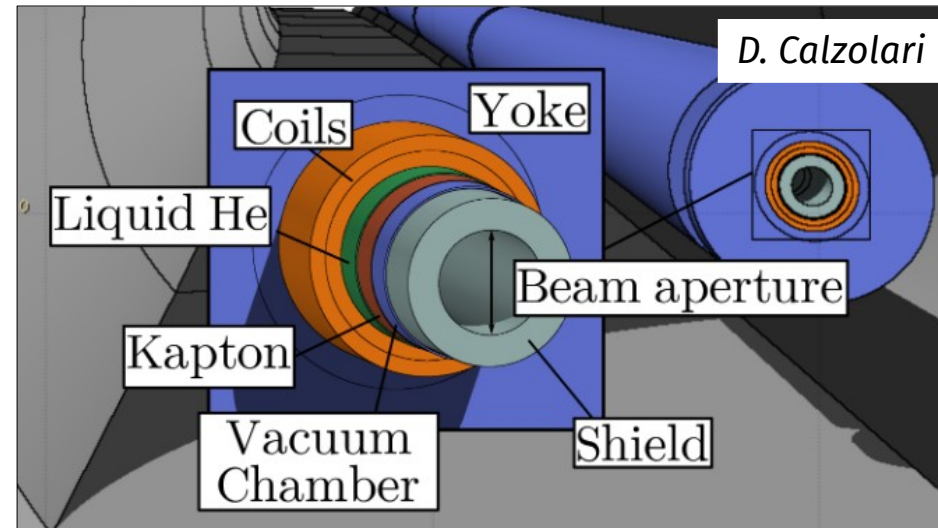
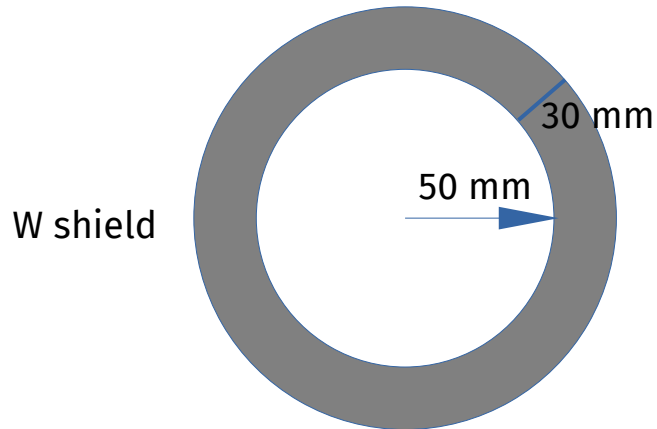
	Unit	Value
Circumference	m	4500
Chamber length	m	4500
Chamber geometry		Circular
Chamber material		Tungsten 300 K / Tungsten 80K Copper 300 K / Tungsten 20 K
Chamber thickness	m	Inf.
Chamber radius	mm	10 to 40
Avg. beta x/y	m	100 / 100

# Impedance simulations parameters: materials

- Past Muon collider studies suggested to use a tungsten liner to intercept muon decay products
  - Decrease the heat load and radiation dose sustained by the magnets
  - Proposal for a liner cooled at 80 K by [N. V. Mokhov et al.](#)
  - Also proposal for a tungsten liner at 300 K, see [M. Green](#)
- Impedance and stability simulations with four materials:  
Copper at 300 K, Copper at 20 K, Tungsten at 80 K, Tungsten at 300 K

# Liner design to protect from decay product

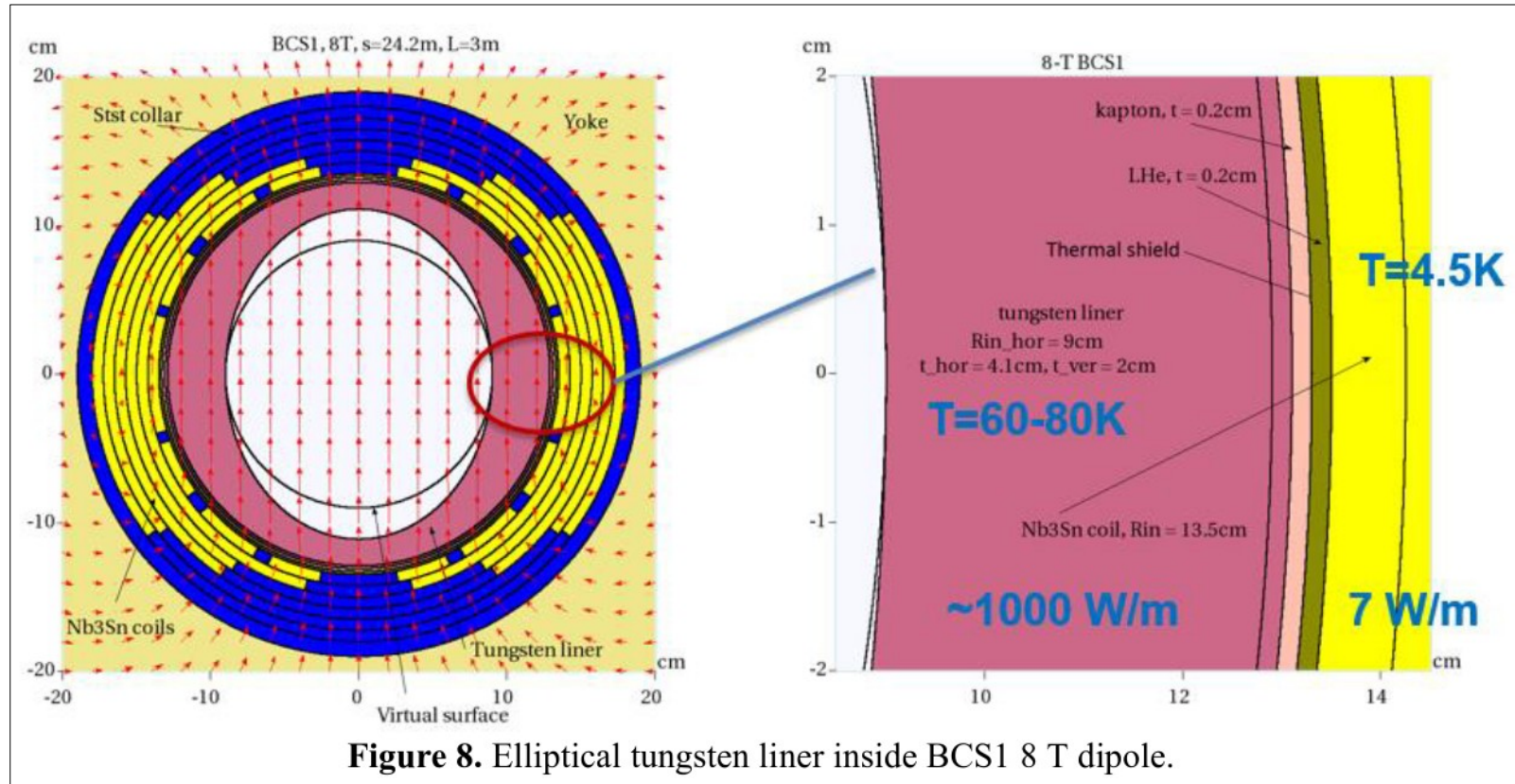
- Power deposition and radiation damage studies done by D. Calzolari et al., presented at IPAC 22
- 30 mm thick, 50 mm inner radius, tungsten shield
- Shield temperature not yet defined





# Liner design to protect from decay product

Liner thickness varies according to magnet type and family



*Tungsten liner design from  
N. V. Mokhov et al.*

# Impedance simulations parameters: materials

- Infinite thickness for all the chambers simulated

Copper at 20 K

	Unit	Value
Magnetic field	T	7
Temperature	K	20
RRR		70
DC resistivity	nOhm m	0.667

Copper at 300 K

	Unit	Value
Magnetic field	T	7
Temperature	K	300
RRR		70
DC resistivity	nOhm m	17.9

Tungsten at 80 K

	Unit	Value
Temperature	K	80
DC resistivity	nOhm m	6.06

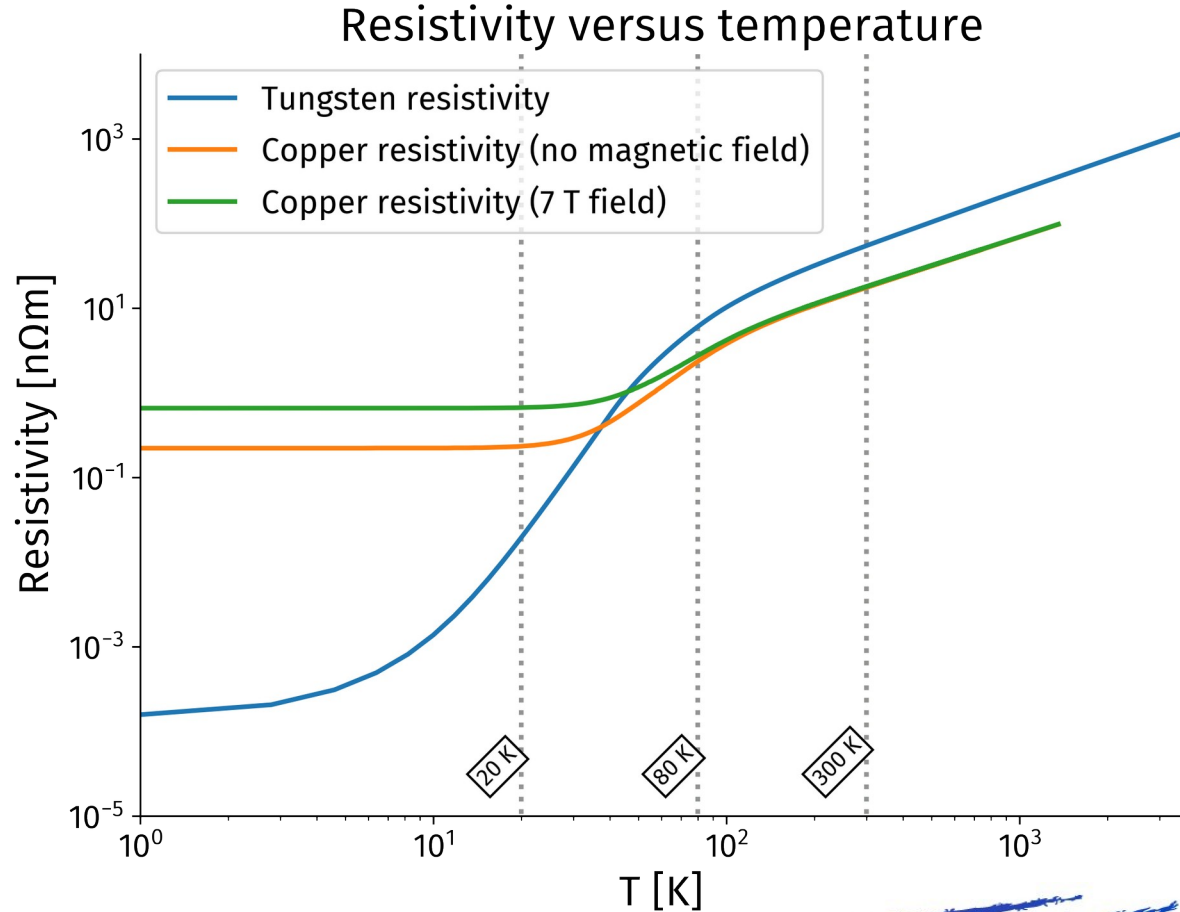
Tungsten at 300 K

	Unit	Value
Temperature	K	300
DC resistivity	nOhm m	54.4



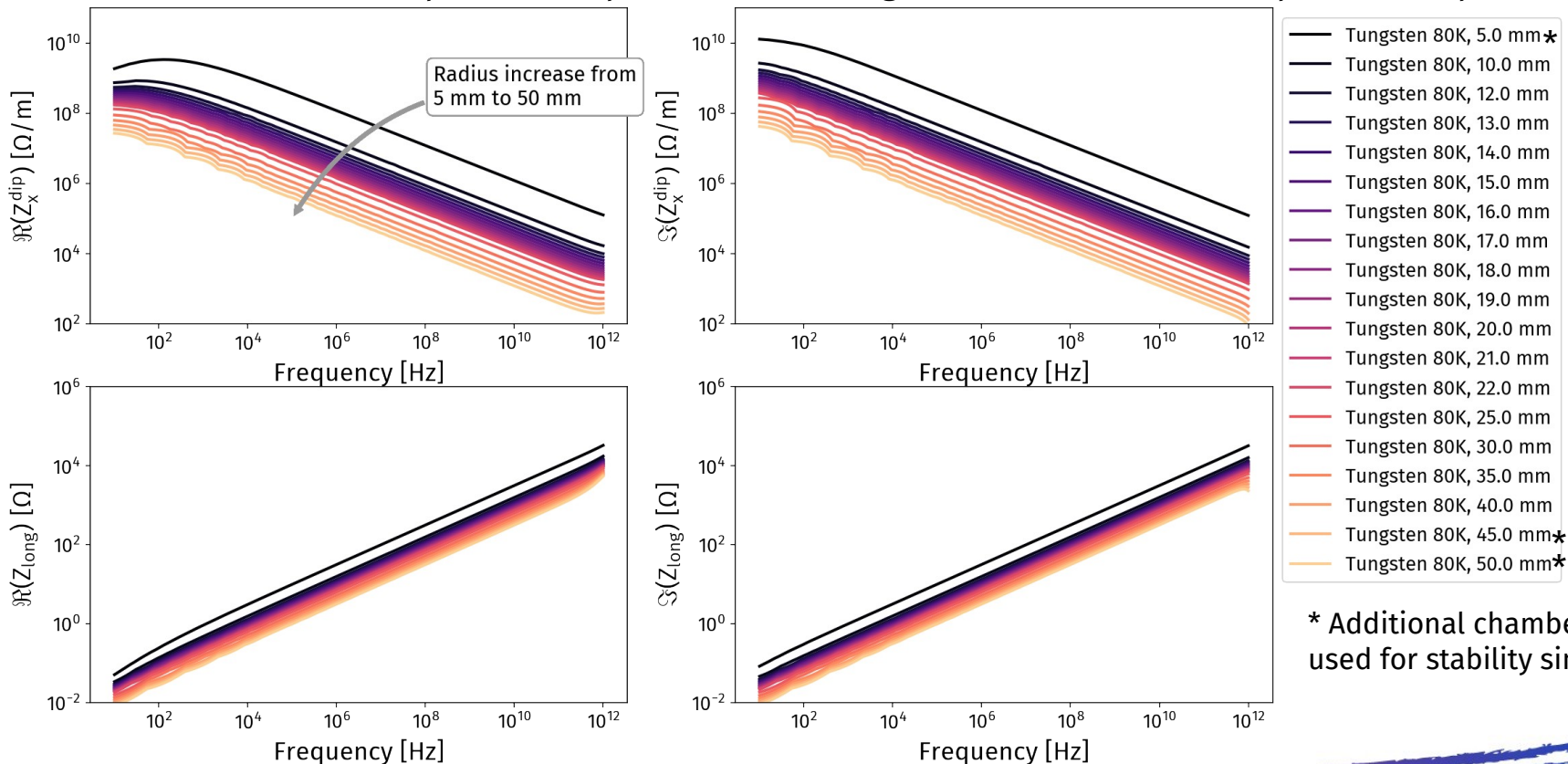
# Impedance simulations parameters: materials

- Resistive wall impedance and wake are proportional to  $\sqrt{\rho}$
- Copper resistivity versus temperature and magnetic field
  - Simon, Drexler and Reed “Properties of copper and copper alloys at cryogenic temperatures”, 1992
- Tungsten resistivity versus temperature
  - Desai et al. “Electrical Resistivity of Selected Elements”, 1984



# Impedance results for chambers in Tungsten at 80 K

Transverse resistive wall impedance depends on  $1/r^3$ , longitudinal resistive wall impedance depends on  $1/r$





# Transverse stability simulation parameters in the 3 TeV collider

- Simulation including longitudinal map (1 RF station) + transverse map + **transverse wakefield** + damper + optionally muon decay
- Tracking over 3000 turns, 5000 macroparticles with PyHEADTAIL, initial intensity  $2.2 \cdot 10^{12}$  muons, transverse emittance 25  **$\mu\text{m rad}$**  (detailed parameters in appendix)
- **Optionally: include muon decay effect**
  - Muon lifetime at 1.5 TeV:  $14285 \cdot 2.2 \text{ us} = 31.4 \text{ ms}$
  - Revolution frequency  $\sim 66 \text{ kHz}$  → **muon lifetime at 1.5 TeV is  $\sim 2100$  turns**



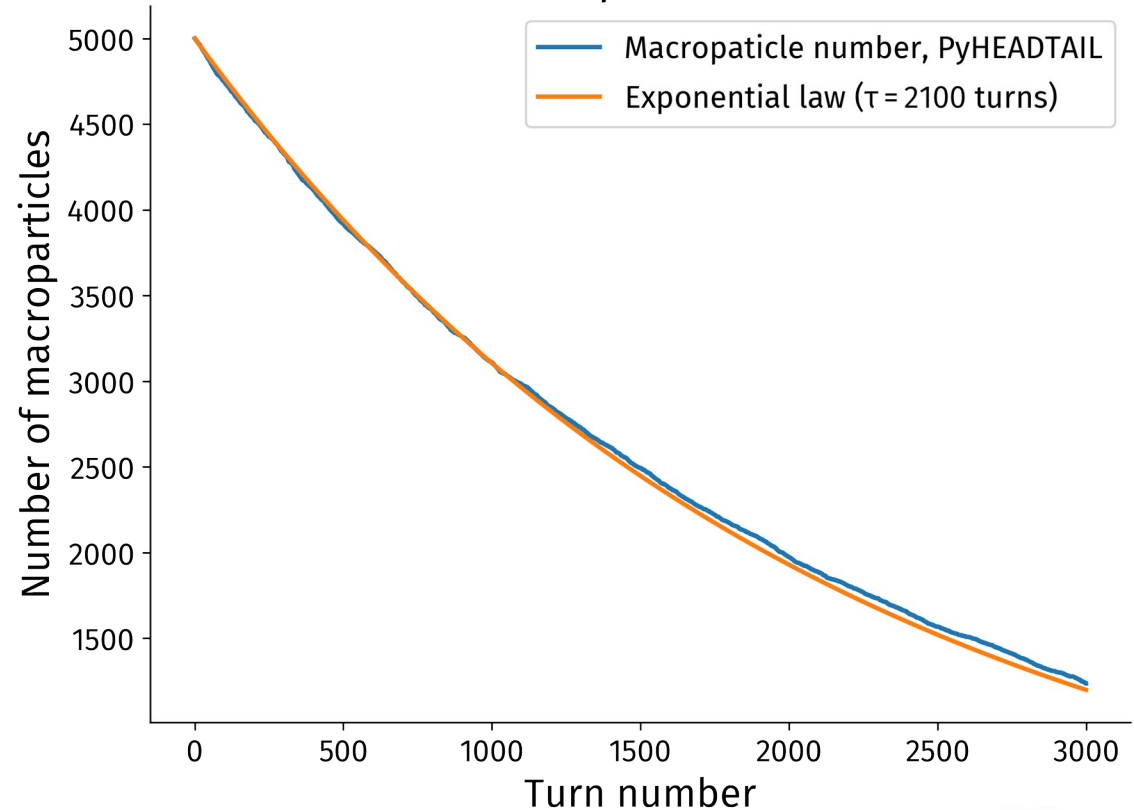
# Transverse stability simulation parameters in the 3 TeV collider

- Scan the **chamber radius from 10 mm to 40 mm**
  - 5 mm radius produces too strong wakefields, numerical errors quickly occur
- Scan the transverse damper from 2 to 500-turn gain + no damper
- Horizontal and vertical planes have the same impedance (circular chamber), and same beam parameters → simulation results identical in the two planes

# Implementation of the muon beam decay

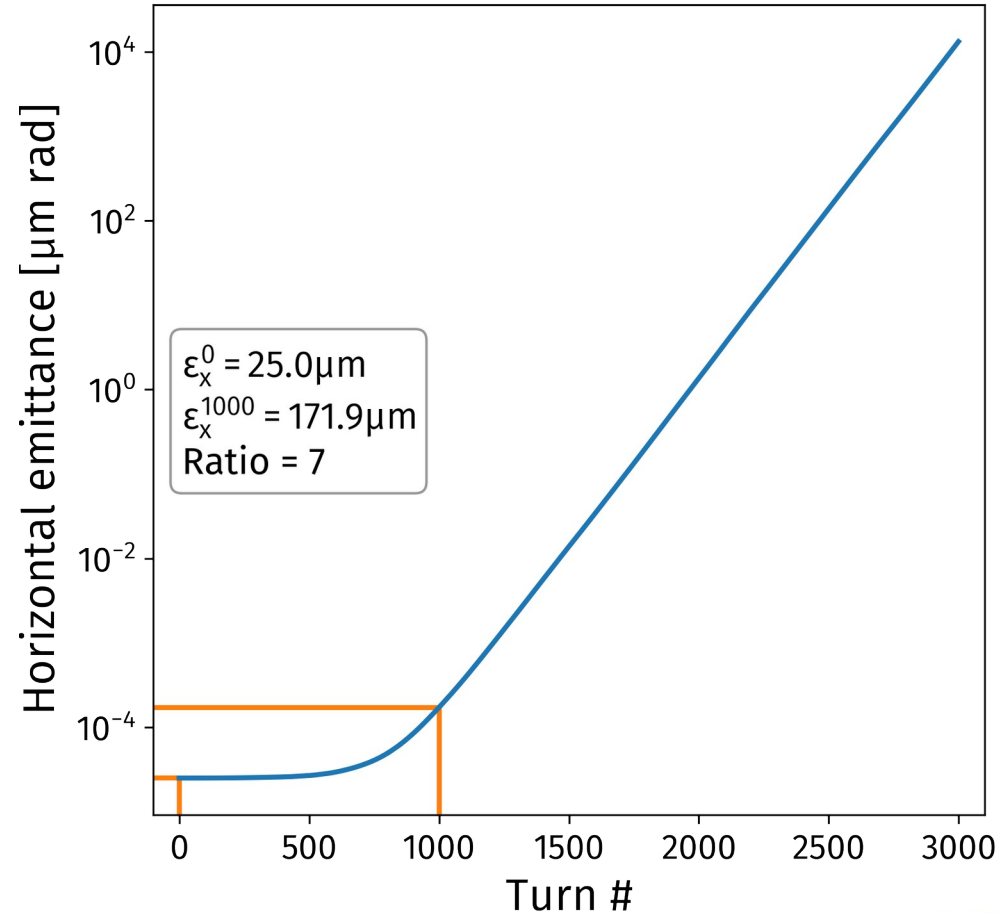
- Decay element in PyHEADTAIL
  - Input: decay time (in number of turns) of the beam
  - Use numpy rand function to randomly select the macroparticle that will be deleted, according to the decay time
- Exponential decay behavior reproduced in simulations
- Bunch intensity reduced by 50 % after  $\ln(2) \cdot 2100 = 1450$  turns

Comparison of macroparticle decay versus exponential law



# Growth ratio plots

- Compute the ratio of emittance after a certain time versus initial emittance (25  $\mu\text{m rad}$ )
- For all damper settings and chamber radius, at different number of turns
- We will look at growth ratios after 2000 turns

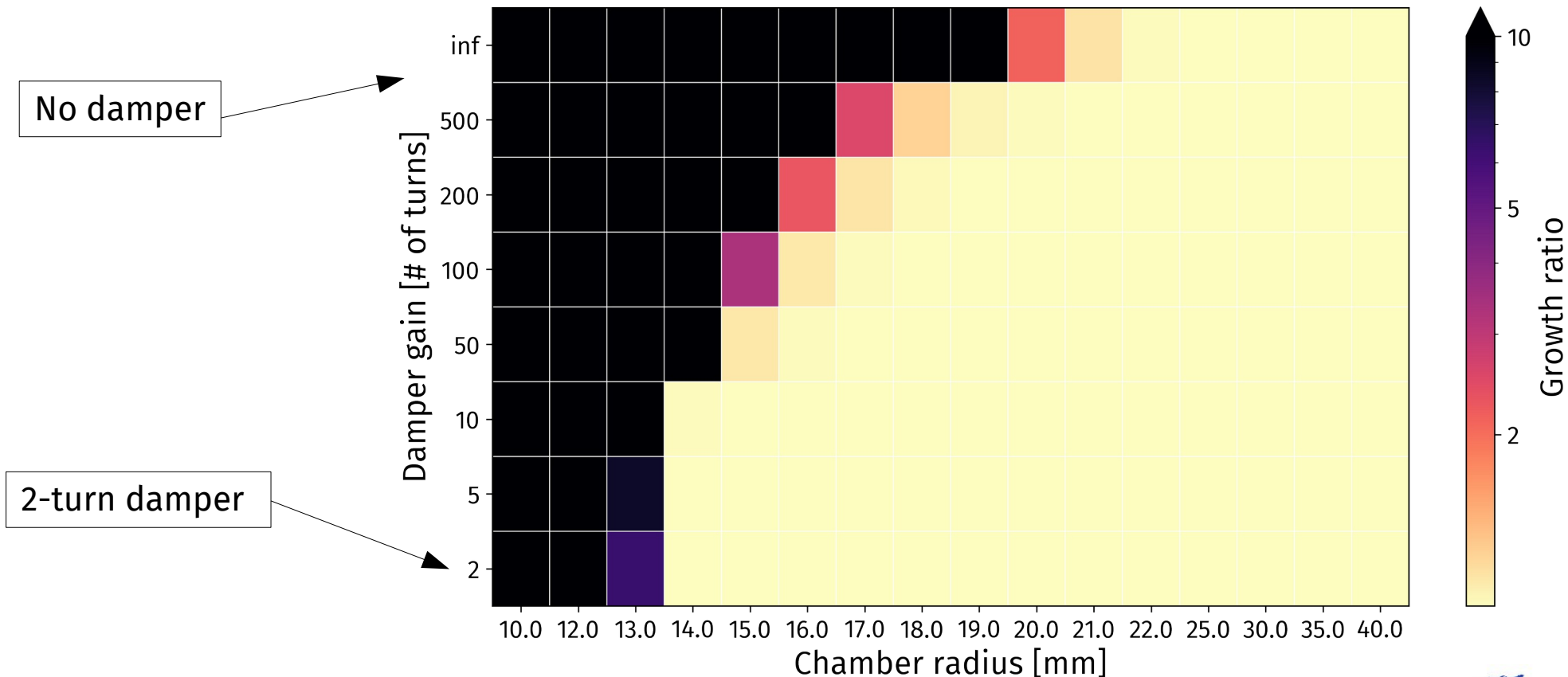




# Simulation results

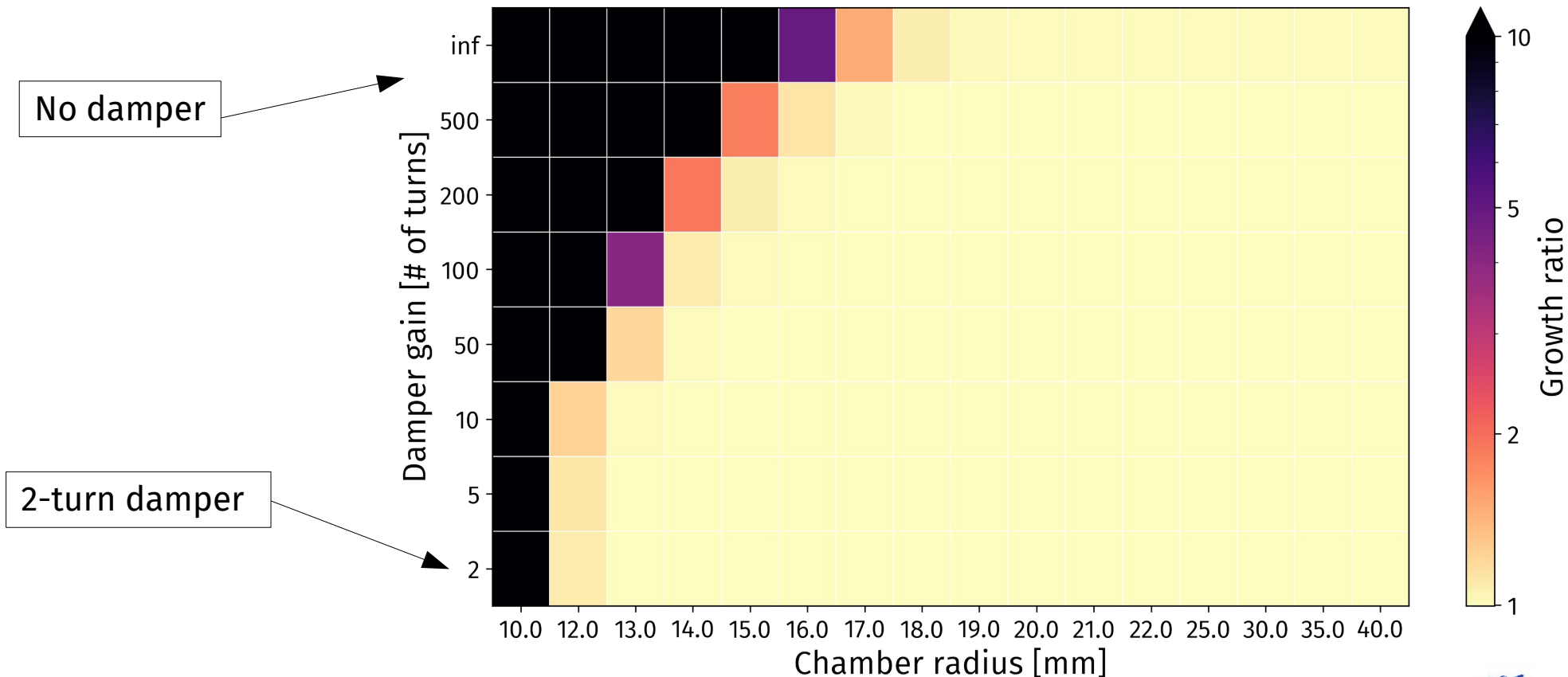
# Tungsten 80 K, after 2000 turns, WITHOUT muon decay

Tungsten at 80 K growth ratio after 2000 turns



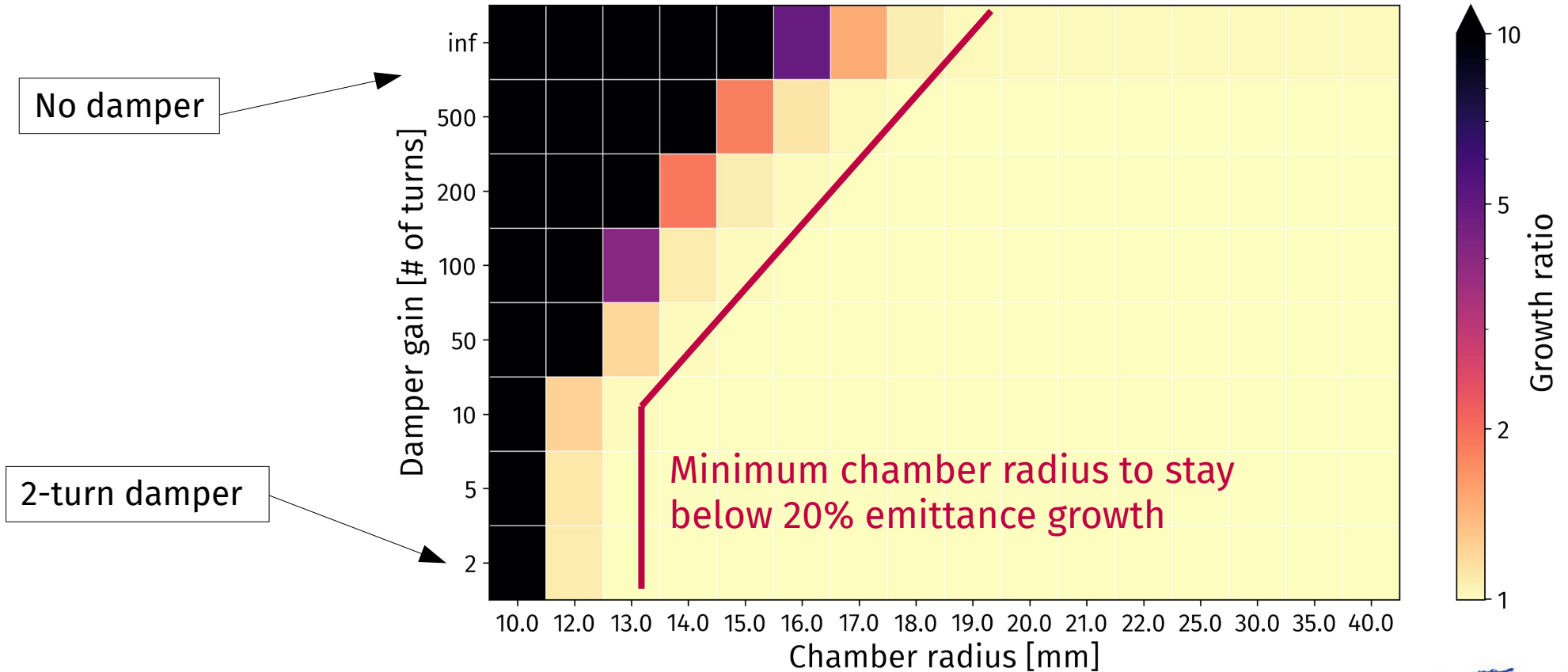
# Tungsten 80 K, after 2000 turns, WITH muon decay

Tungsten at 80 K, with muon decay growth ratio after 2000 turns



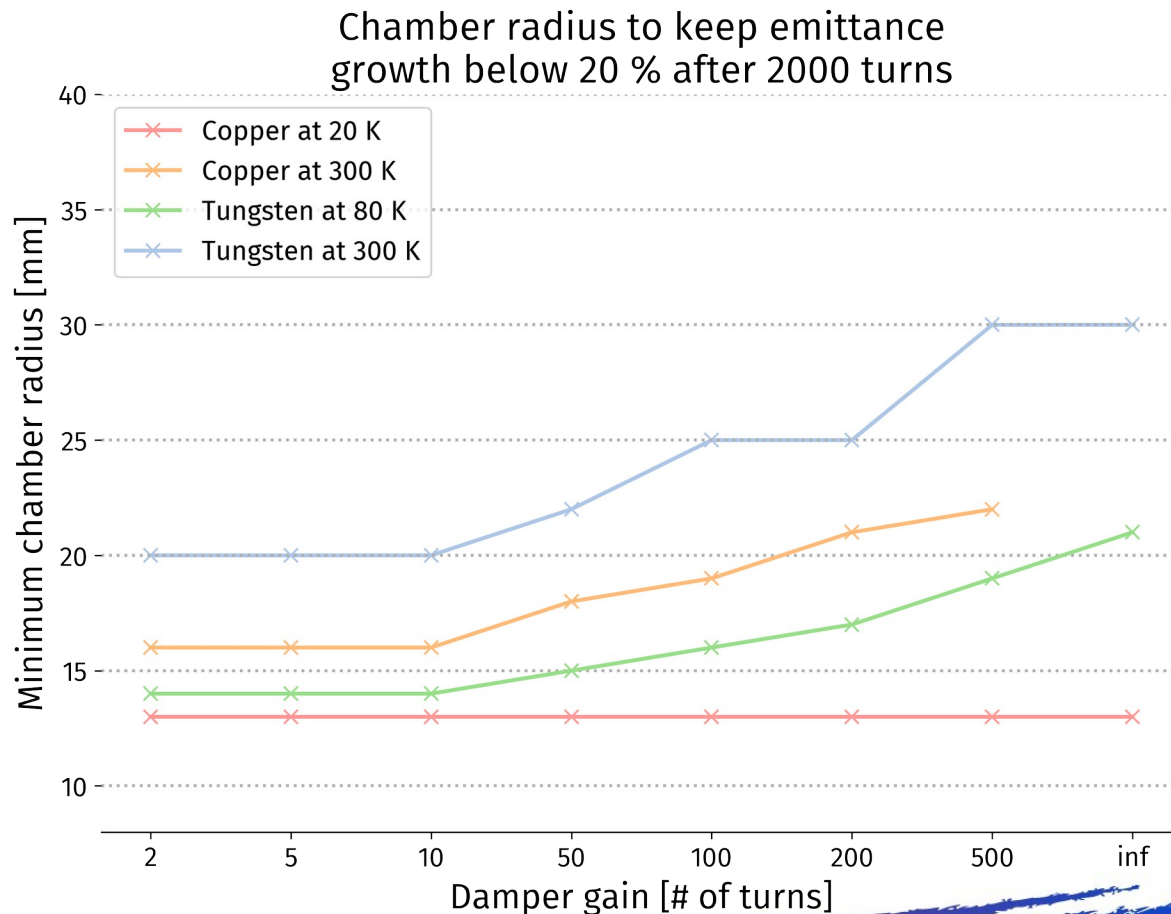
# Tungsten 80 K, after 2000 turns, WITH muon decay

Tungsten at 80 K, with muon decay growth ratio after 2000 turns



# Minimum chamber radius versus material, without muon decay

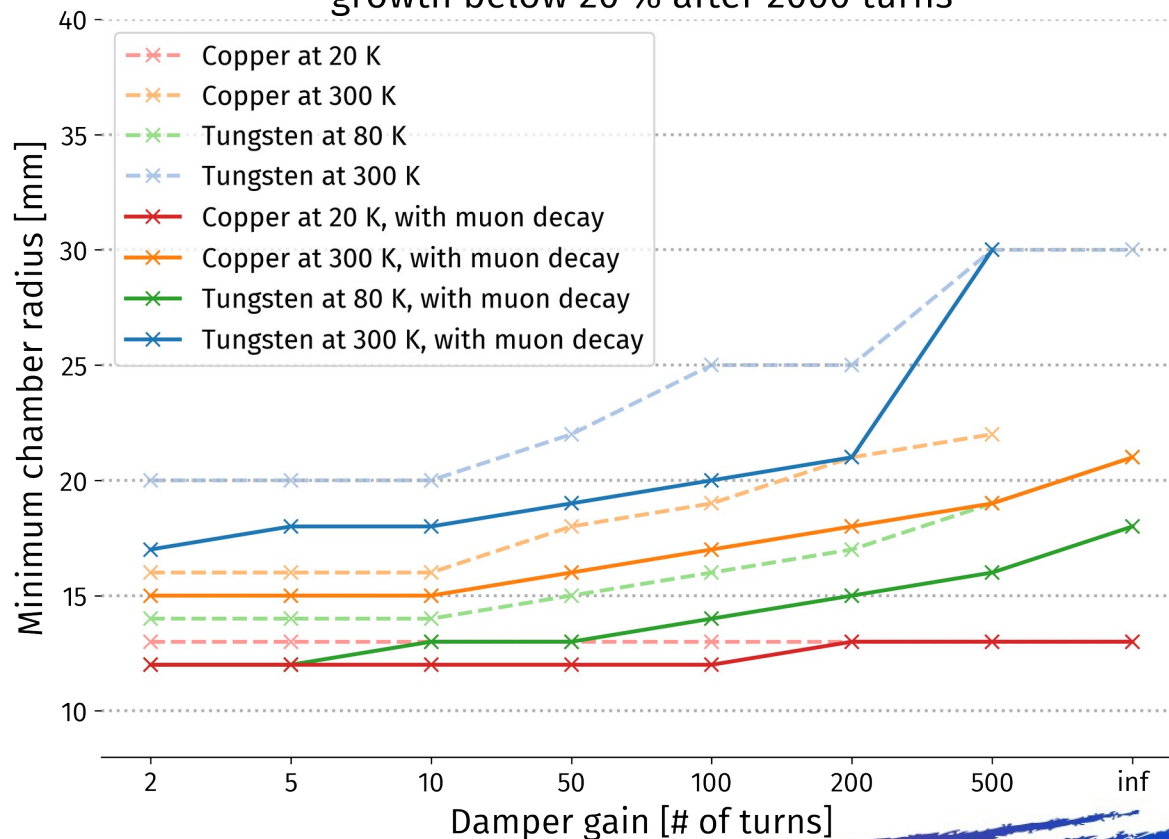
- Summary plot for the case **without muon decay**
- For every damper gain, find the chamber radius such as the **emittance growth stays below 20 % after 2000 turns**
  - No point for a damper setting means that the beam was always unstable



# Minimum chamber radius versus material, with muon decay

- Summary plot for the case **without and with muon decay**
- For every damper gain, find the chamber radius such as the **emittance growth stays below 20 % after 2000 turns**
  - No point for a damper setting means that the beam was always unstable

Chamber radius to keep emittance growth below 20 % after 2000 turns







# Summary of transverse stability simulation in the 3 TeV collider

- Simulation including longitudinal map (1 RF station) + transverse map + **transverse wakefield** + damper + **optionnaly muon decay**
- Tracking over 3000 turns, 5000 macroparticles with PyHEADTAIL
- Overall, chamber radii below 18 mm are challenging damper-wise or require cryogenic material
- Radii between 20 and 30 mm allow to use all material with classic damper setting (100, 200 or 500-turn damping)
- Muon decay has a beneficial effect on transverse beam stability
  - Gain between 1 and 5 mm on chamber radius for a given material and damper setting



# Possible next steps for the colliders

- Ongoing: repeat the study for the 10 TeV c.o.m collider (10 km circumference)
- Investigate more complex chamber geometries
- If we want to use tighter ( $< 17$  mm) beam chamber, investigate supplementary mitigation measures for beam instabilities
  - Effect of sextupoles (chromaticity)
  - Effect of octupoles (tune spread to enhance Landau damping)

# *Appendix*

# Stability simulation parameters

## Machine parameters

	Unit	Value
Circumference	m	4500
Beam momentum	GeV/c	1500
Rev. frequency	kHz	66
RF frequency	MHz	800
Harmonic number		12008
RF voltage	MV	250
$\alpha_p$		-2.15e-6
Avg. beta x/y	m	100 / 100
Chromaticity $Q'_x/Q'_y$		0 / 0
Detuning from octupoles x/y	$m^{-1}$	0 / 0

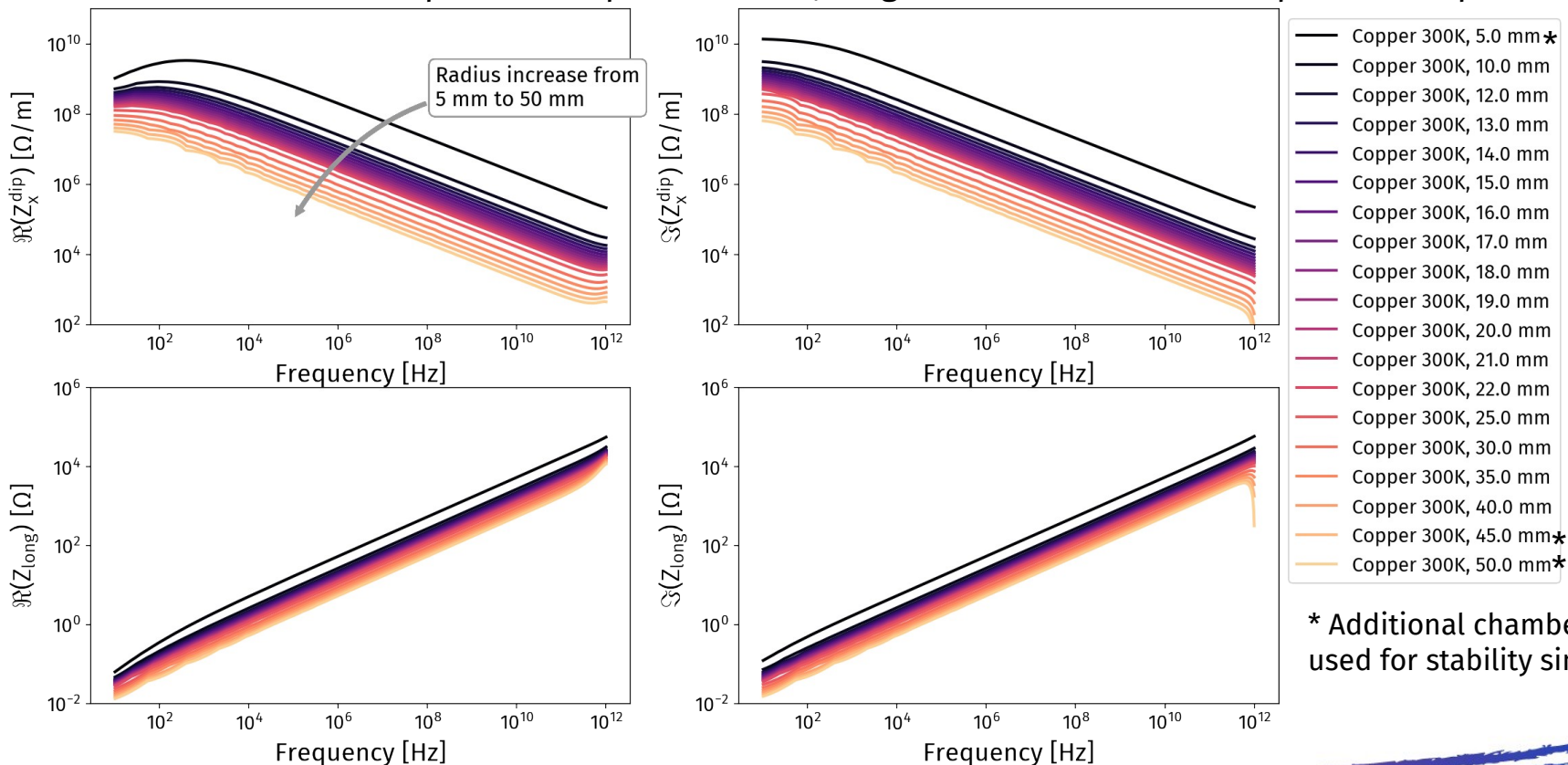
	Unit	Value
Synchrotron tune $Q_s$		0.000829
Synchrotron period	turns	1206
<b>Bunch length <math>1\sigma</math></b>	<b>mm</b>	<b>5</b>
<b>Bunch intensity</b>	<b>Particles per bunch</b>	<b>2.2e12</b>
$\epsilon_x / \epsilon_y$	$\mu\text{m rad}$	<b>25</b>
# of macroparticles		5000

## Scanned parameters

	Unit	Value
Chamber radius	mm	10 to 40
Transverse damper		2 to 500 turns/No damper

# Impedance for Copper at 300 K

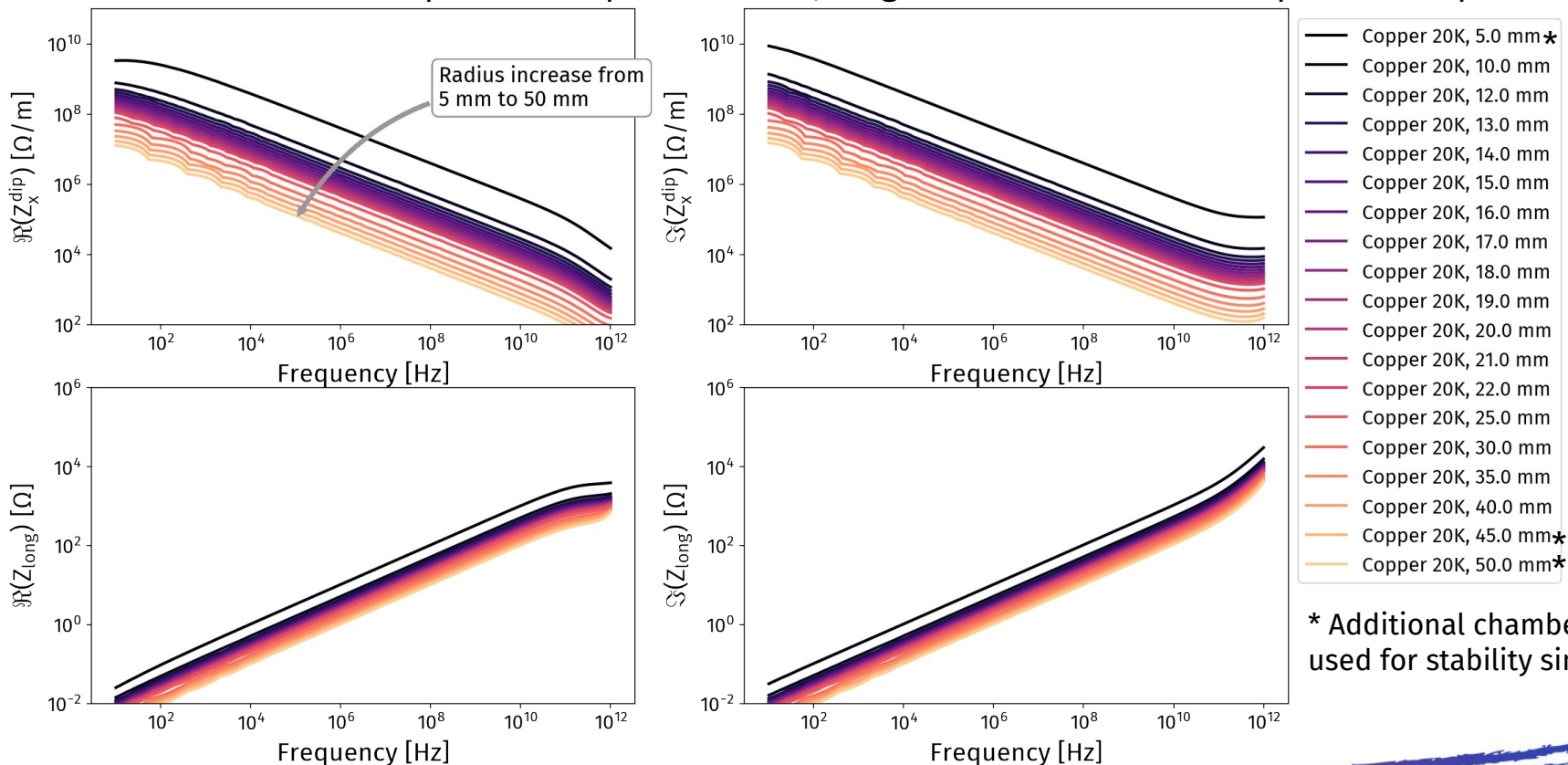
Transverse resistive wall impedance depends on  $1/r^3$ , longitudinal resistive wall impedance depends on  $1/r$



\* Additional chamber radii not used for stability simulations

# Impedance for Copper at 20 K

Transverse resistive wall impedance depends on  $1/r^3$ , longitudinal resistive wall impedance depends on  $1/r$

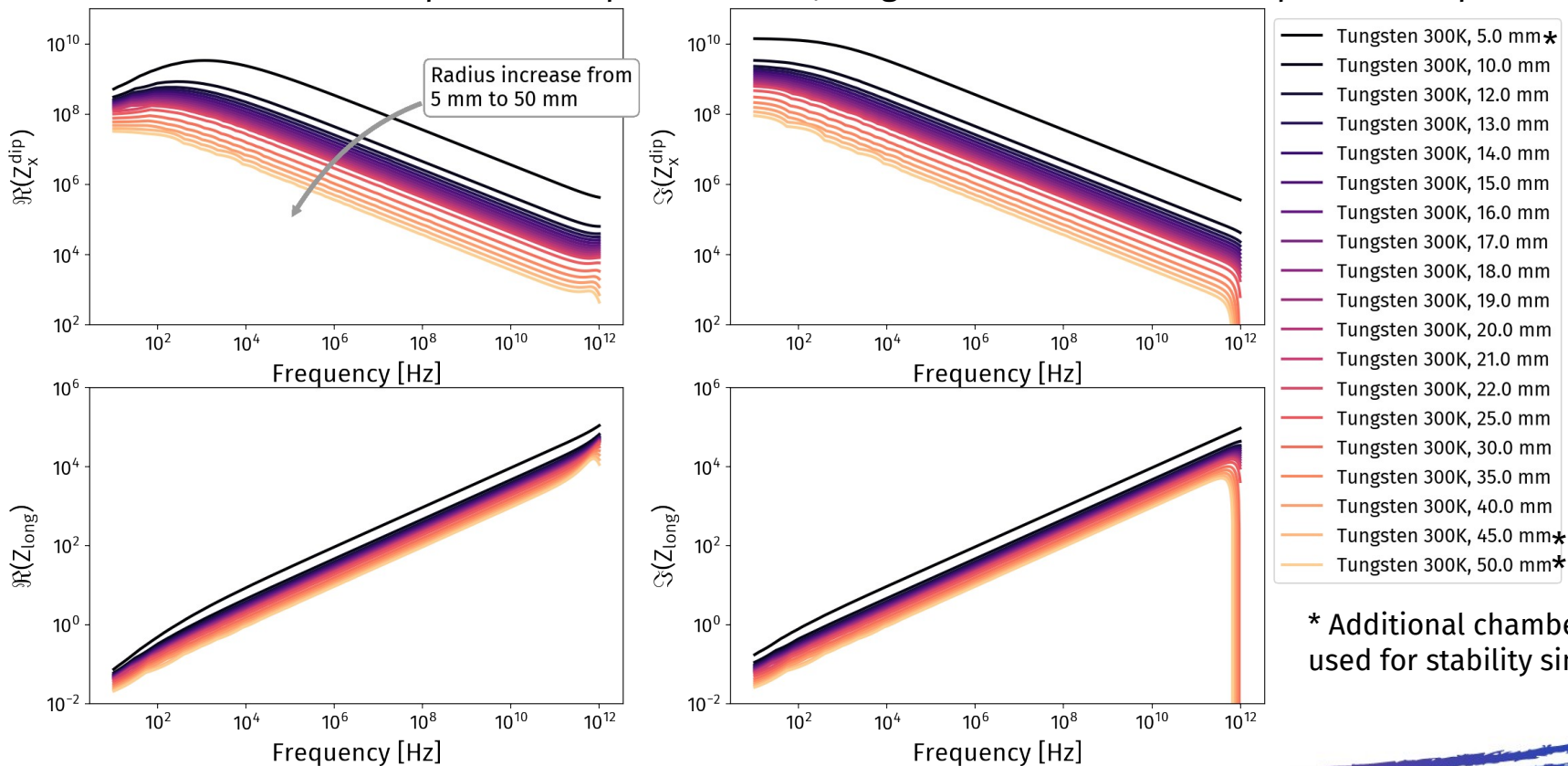


\* Additional chamber radii not used for stability simulations



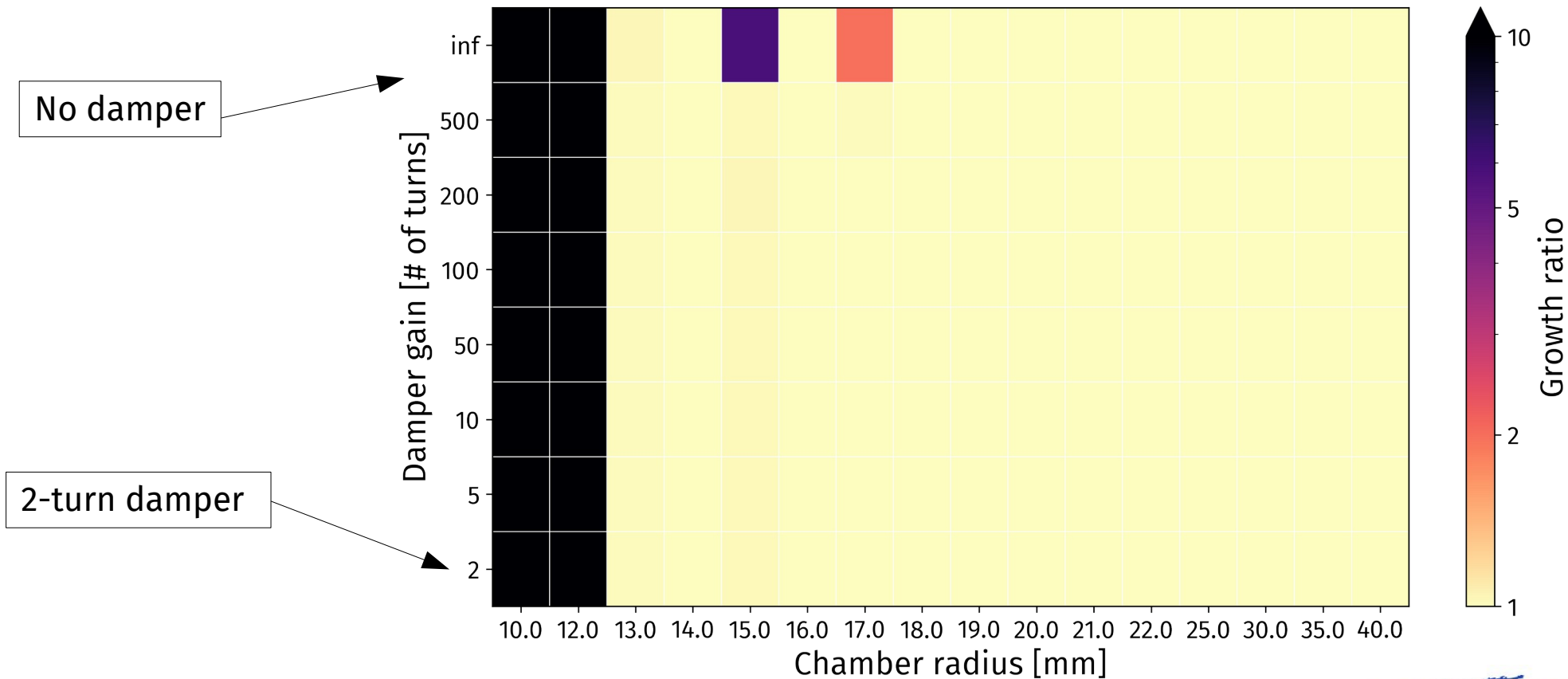
# Impedance for Tungsten at 300 K

Transverse resistive wall impedance depends on  $1/r^3$ , longitudinal resistive wall impedance depends on  $1/r$



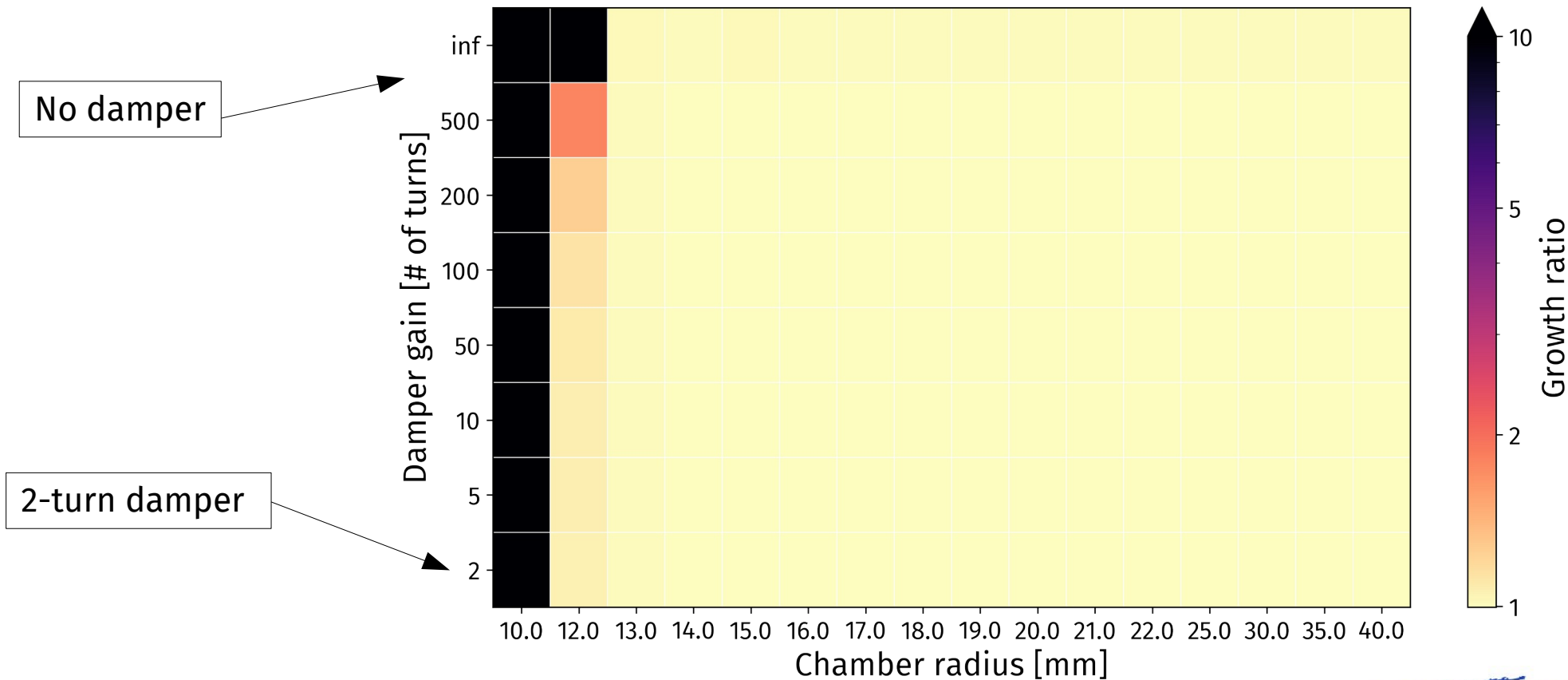
# Copper 20 K, after 2000 turns

Copper at 20 K growth ratio after 2000 turns



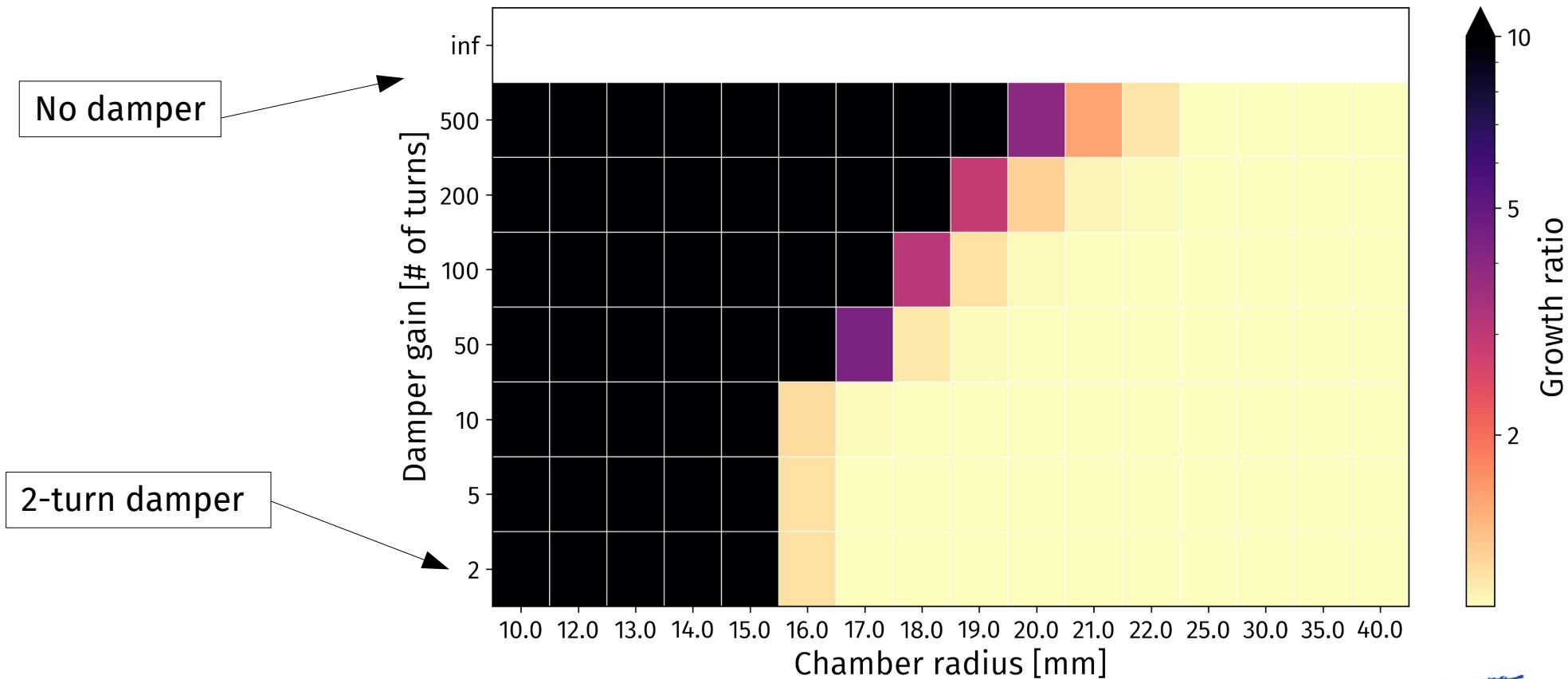
# Copper 20 K, after 2000 turns, with muon decay

Copper at 20 K, with muon decay growth ratio after 2000 turns



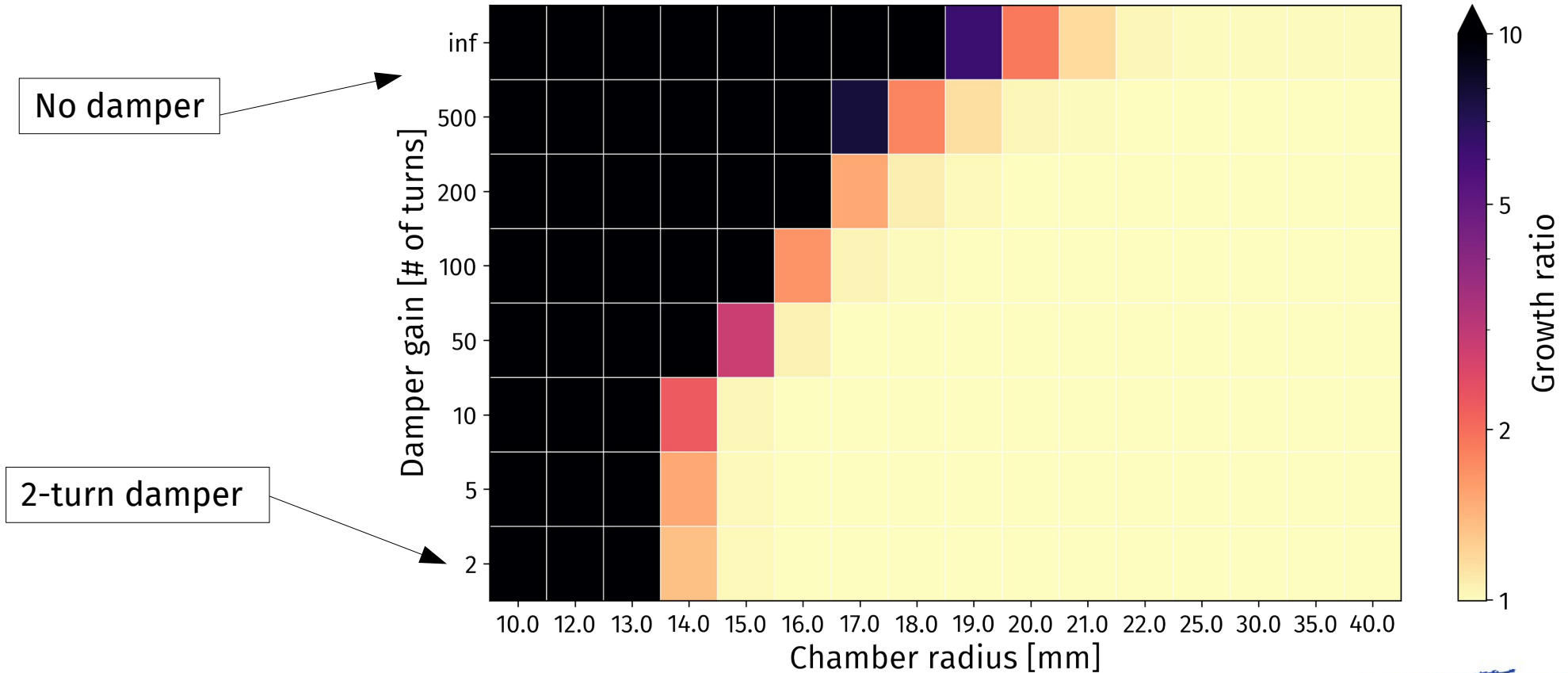
# Copper 300 K, after 2000 turns

Copper at 300 K growth ratio after 2000 turns



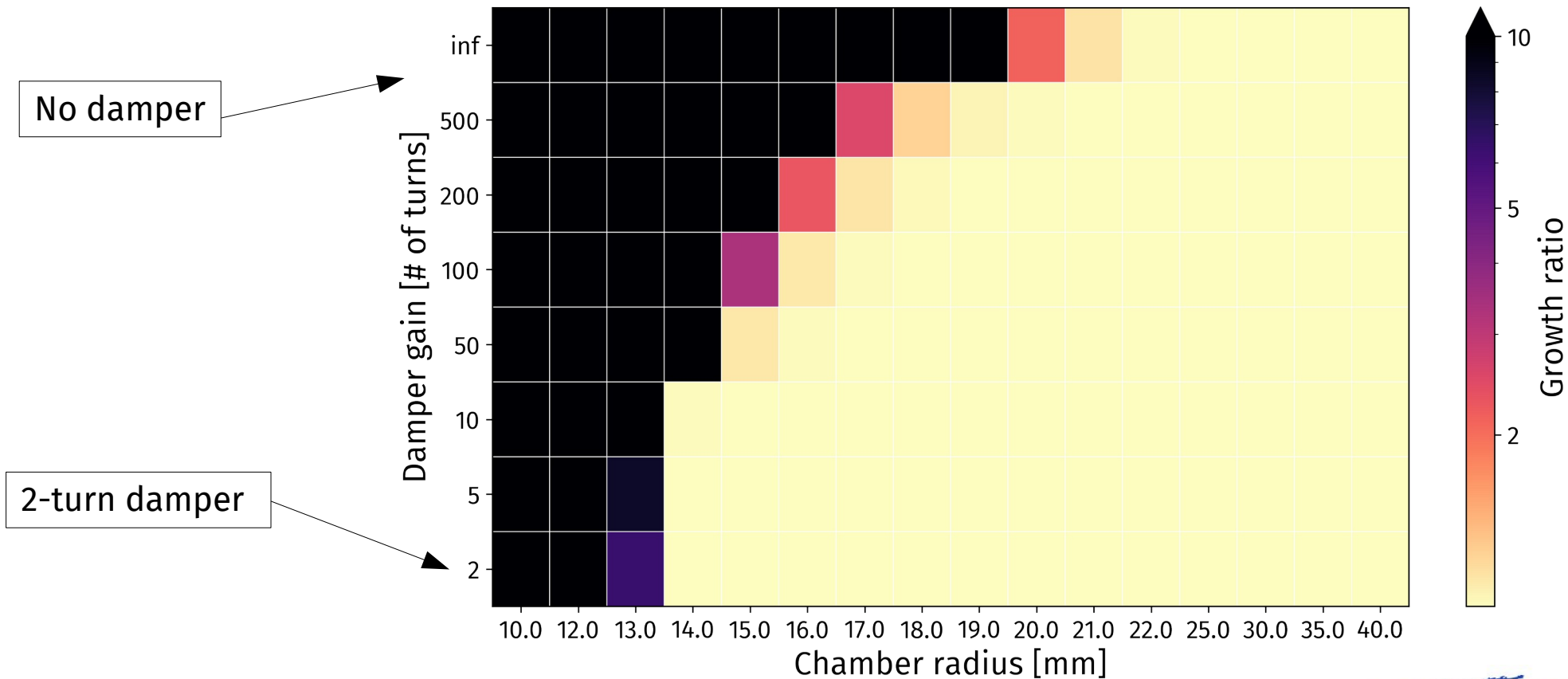
# Copper 300 K, after 2000 turns, with muon decay

Copper at 300 K, with muon decay growth ratio after 2000 turns



# Tungsten 80 K, after 2000 turns

Tungsten at 80 K growth ratio after 2000 turns

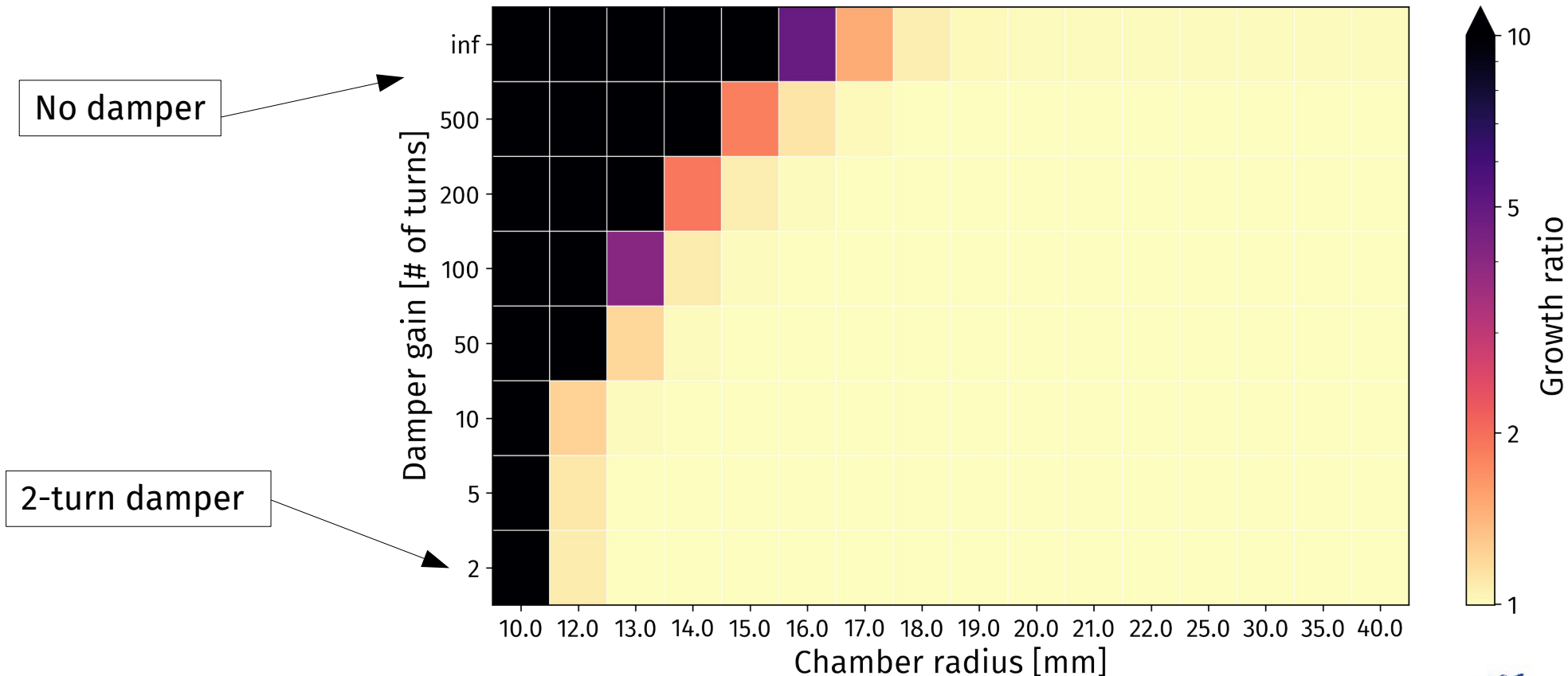




# Tungsten 80 K, after 2000 turns, with muon decay

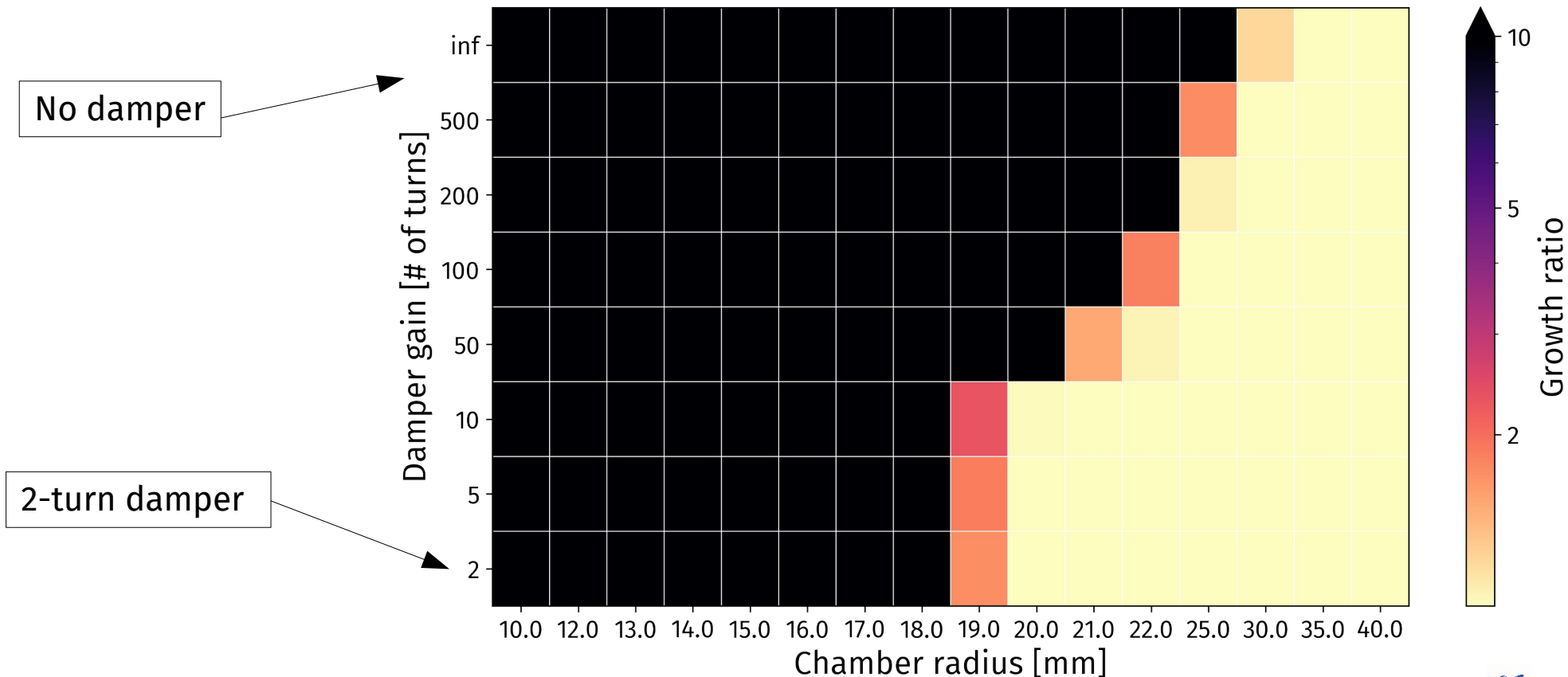
## decay

Tungsten at 80 K, with muon decay growth ratio after 2000 turns



# Tungsten 300 K, after 2000 turns

Tungsten at 300 K growth ratio after 2000 turns



# Tungsten 300 K, after 2000 turns, with muon decay

## decay

Tungsten at 300 K, with muon decay growth ratio after 2000 turns

